

SUPERMICR[®]

Twin Architecture

Most Optimized Server Platforms for Enterprise, HPC and Cloud Computing

Highest Performance-per-Watt/per-Dollar

Broadest Spectrum of Twin Products with

- 16 DIMMs and 512GB DDR3 1600 MHz Memory per node
- Redundant Efficiency Platinum Level (95%) Digital Power Supplies
- Up to 6x 3.5" or 12x 2.5" SAS2 / SATA3 HDDs / SSDs per node
- PCI-E 3.0 x8 MicroLP slot for ConnectX-3 FDR IB or 10 GbE SFP+
- Server Management with onboard IPMI 2.0 / Dedicated LAN
- Dual Intel[®] Xeon[®] Processor E5-2600 product family

Twin Innovation

Supermicro's patented Twin Architecture with up to 16 DIMMs per node for Highest Performance is the foundation of the most advanced server platforms in HPC/ Data Center, Cloud Computing and Enterprise IT applications. These high performance, high density systems feature optimum airflow for energy efficient cooling, easy maintenance and high availability with hot-swappable nodes and redundant power supply modules. These systems also feature the latest CPU and interconnect technologies for maximum processing performance and data throughput.



Node 1 | Node 2 | Node 3 | Node 4

2U Twin²[®]

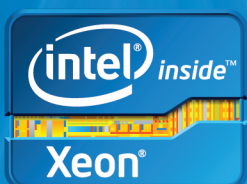
SYS-6027TR-H+ Series
4 Hot-Swappable DP Nodes in 2U



Node 1 | Node 2

2U Twin

SYS-2027TR-D+ Series
2 Hot-Swappable DP Nodes in 2U



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